



## 4M x 4 CMOS DRAM WITH FAST PAGE MODE, 3.3V

### AVAILABLE AS MILITARY SPECIFICATIONS

- MIL-STD-883

### FEATURES

- Fast Page Mode Operation
- CAS\-before-RAS\ Refresh Capability
- RAS\-only and Hidden Refresh Capability
- Self-refresh Capability
- Fast Parallel Test Mode Capability
- TTL Compatible Inputs and Outputs
- Early Write or Output Enable Controlled Write
- JEDEC Standard Pinout
- Single +3.3V ( $\pm 10\%$ ) Power Supply

### OPTIONS

- Timing
 

60ns access	-6
70ns access	-7
- Package
 

Plastic TSOP, 24-pin	DG
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- Operating Temperature Ranges
 

Military (-55°C to +125°C)	XT
Industrial (-40°C to +85°C)	IT

### MARKINGS

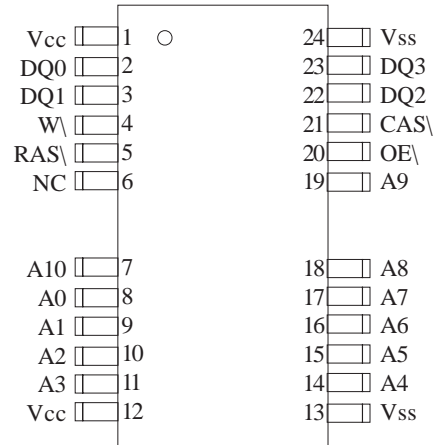
### GENERAL DESCRIPTION

The Austin Semiconductor, Inc. AS4C4M4DG is a 4,194,304 x 4 bit Fast Page Mode CMOS DRAM offering high speed random access of memory cells within the same row. This device features a +5V ( $\pm 10\%$ ) power supply, refresh cycle (2K), and fast access times (60 and 70ns). Other features include CAS\-before-RAS\, RAS\-only refresh, self-refresh operation (128ms refresh period), and Hidden refresh capabilities. This 4M x 4 Fast Page Mode DRAM is fabricated using an advanced CMOS process to realize high bandwidth, low power consumption and high reliability. It may be used as main memory for high level computers, micro-computers and personal computers.

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### PIN ASSIGNMENT

(Top View)



### PIN ASSIGNMENT

PIN	FUNCTION
A0 - A10	Address Inputs
DQ0 -DQ3	Data In/Out
V <sub>SS</sub>	Ground
RAS\	Row Address Strobe
CAS\	Column Address Strobe
W\	Read/Write Input
OE\	Data Output Enable
V <sub>CC</sub>	Power (+5V)
NC	No Connect

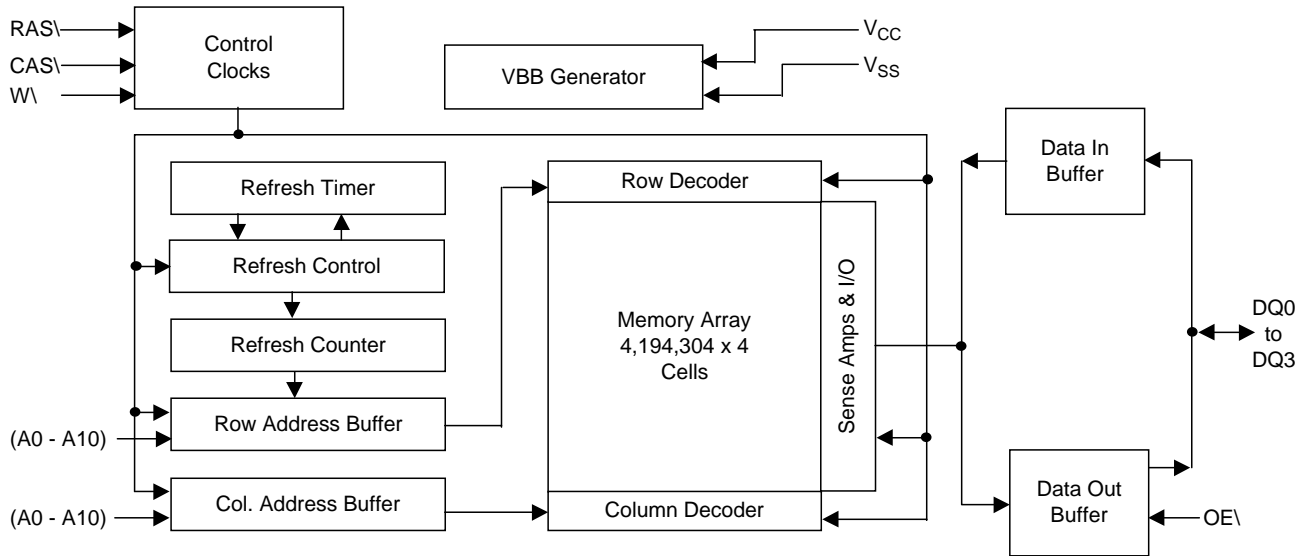
### ACTIVE POWER DISSIPATION

SPEED	2K	UNITS
-6	550	mW
-7		mW

### PERFORMANCE RANGE

SPEED	t <sub>RAC</sub>	t <sub>CAC</sub>	t <sub>RC</sub>	t <sub>PC</sub>	UNITS
-6	60	15	110	40	ns
-7					ns

## FUNCTIONAL BLOCK DIAGRAM



### ABSOLUTE MAXIMUM RATINGS\*

Voltage on any pin relative to $V_{CC}$ ( $V_{IN}$ , $V_{OUT}$ )	.....	-0.5V to +4.6V
Voltage on $V_{CC}$ supply relative to $V_{SS}$ ( $V_{CC}$ )	.....	-0.5V to +4.6V
Storage Temperature ( $T_{stg}$ )	.....	-55°C to +150°C
Power Dissipation ( $P_D$ )	.....	1W
Short Circuit Output Current ( $I_{OS}$ Address)	.....	50mA

\*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Junction temperature depends upon package type, cycle time, loading, ambient temperature and airflow, and humidity (plastics).

### ELECTRICAL CHARACTERISTICS AND RECOMMENDED OPERATING CONDITIONS

(-55°C ≤  $T_A$  ≤ +125°C & -40°C ≤  $T_A$  ≤ +85°C ;  $V_{CC} = 3.3V \pm 0.3V$ )

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS
Supply Voltage	$V_{CC}$	3.0	3.3	3.6	V
Ground	$V_{SS}$	0	0	0	V
Input High Voltage	$V_{IH}$	2.0	---	$V_{CC} + 0.3^1$	V
Input Low Voltage	$V_{IL}$	-0.3 <sup>2</sup>	---	0.8	V

**NOTES:**

1.  $V_{CC} + .13V/15ns$ , Pulse width is measured at  $V_{CC}$
2.  $-1.3V/15ns$ , Pulse width is measured at  $V_{SS}$



**ELECTRICAL CHARACTERISTICS AND RECOMMENDED DC OPERATING CONDITIONS**

( $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$  &  $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$  ;  $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$ )

PARAMETER	SYMBOL	MIN	MAX	UNITS
Input Leakage Current (any input $0 \leq V_{IN} \leq V_{IN} + 0.3\text{V}$ , all other input pins not under test = 0 Volt)	$I_{I(L)}$	-5	5	$\mu\text{A}$
Output Leakage Current (Data out is disabled, $0\text{V} \leq V_{OUT} \leq V_{CC}$ )	$I_{O(L)}$	-5	5	$\mu\text{A}$
Output High Voltage ( $I_{OH} = -2\text{mA}$ )	$V_{OH}$	2.4	---	V
Output Low Voltage ( $I_{OL} = 2\text{mA}$ )	$V_{OL}$	---	0.4	V

SYMBOL	PARAMETERS	MAX		UNITS
		-60	-70	
$I_{CC1}^*$	Operating Current (RAS\ and CAS\, Address cycling @ $t_{RC} = \text{MIN}$ ), Power = Don't Care	100		
$I_{CC2}$	Standby Current (RAS\ = CAS\ = W\ = $V_{IH}$ ) Power = Normal L	1		
$I_{CC3}^*$	RAS\-only Refresh Current (CAS\ = $V_{IH}$ , RAS\, Address cycling @ $t_{RC} = \text{MIN}$ ), Power = Don't Care	100		
$I_{CC4}^*$	Fast Page Mode Current (RAS\ = $V_{IL}$ , CAS\, Address cycling @ $t_{PC} = \text{MIN}$ ), Power = Don't Care	80		
$I_{CC5}$	Standby Current (RAS\ = CAS\ = W\ = $V_{CC} - 0.2\text{V}$ ) Power = Normal L	200		
$I_{CC6}^*$	CAS\ -BEFORE-RAS\ Refresh Current (RAS\ and CAS\ cycling @ $t_{RC} = \text{MIN}$ ), Power = Don't Care	100		
$I_{CC7}$	Battery back-up current, Average power supply current, Battery back-up mode, Input high voltage ( $V_{IH}$ ) = $V_{CC} - 0.2\text{V}$ , Input low voltage ( $V_{IL}$ ) = 0.2V, CAS\ = 0.2V, DQ = Don't care, $T_{RC} = 31.25\mu\text{s}$ (4K/L-ver), $62.5\mu\text{s}$ (2K/L-ver), $T_{RAS} = T_{RAS \text{ min}} \sim 300\text{ns}$	250		
$I_{CCS}$	Self Refresh Current, RAS\ = CAS\ = 0.2V, W\ = OE\ = A0 ~ A11 = $V_{CC} - 0.2\text{V}$ or 0.2V, DQ0 ~ DQ3 = $V_{CC} - 0.2\text{V}$ , 0.2V or Open	200		

**NOTES:**

\* $I_{CC1}$ ,  $I_{CC3}$ ,  $I_{CC4}$  and  $I_{CC6}$  are dependent on output loading and cycle rates. Specified values are obtained with the output open.  $I_{CC}$  is specified as an average current. In  $I_{CC1}$ ,  $I_{CC3}$ , and  $I_{CC6}$  address can be changed maximum once while RAS\ =  $V_{IL}$ . In  $I_{CC4}$ , address can be changed maximum once within one fast page mode cycle time,  $t_{PC}$ .



# 16 Meg FPM DRAM AS4LC4M4

Austin Semiconductor, Inc.

### CAPACITANCE (f = 1MHz ; V<sub>cc</sub> = 3.3V ±0.3V)

PARAMETER	SYMBOL	MAX	UNITS
Input capacitance (A0 - A11)	C <sub>IN1</sub>	5	pF
Input capacitance (RAS\, CAS\, W\, OE\)	C <sub>IN2</sub>	7	pF
Output capacitance (DQ0 - DQ3)	C <sub>DQ</sub>	7	pF

### ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS<sup>1,2</sup>

(-55°C ≤ T<sub>A</sub> ≤ +125°C & -40°C ≤ T<sub>A</sub> ≤ +85°C; V<sub>cc</sub> = 3.3V ±0.3V; V<sub>IH</sub>/V<sub>IL</sub> = 2.0/0.8V; V<sub>OH</sub>/V<sub>OL</sub> = 2.0/0.8V)

SYMBOL	PARAMETER	-60		-70		UNITS	NOTES
		MIN	MAX	MIN	MAX		
t <sub>RC</sub>	Random read or write cycle time	110				ns	
t <sub>RWC</sub>	Read-modify-write cycle time	155				ns	3, 4, 10
t <sub>RAC</sub>	Access time from RAS\		60			ns	3, 4, 5
t <sub>CAC</sub>	Access time from CAS\		15			ns	3, 10
t <sub>AA</sub>	Access time from column address		30			ns	3
t <sub>CLZ</sub>	CAS\ to output in Low-Z	0				ns	6
t <sub>OFF</sub>	Output buffer turn-off delay	0	15			ns	2
t <sub>T</sub>	Transition time (raise and fall)	3	50			ns	
t <sub>RP</sub>	RAS\ precharge time	40				ns	
t <sub>RAS</sub>	RAS\ pulse width	60	10K			ns	
t <sub>RSH</sub>	RAS\ hold time	15				ns	
t <sub>CSH</sub>	CAS\ hold time	60				ns	
t <sub>CAS</sub>	CAS\ pulse width	15	10K			ns	
t <sub>RCD</sub>	RAS\ to CAS\ delay time	20	45			ns	4
t <sub>RAD</sub>	RAS\ to column address delay time	15	30			ns	10
t <sub>CRP</sub>	CAS\ to RAS\ precharge time	5				ns	
t <sub>ASR</sub>	Row address set-up time	0				ns	
t <sub>RAH</sub>	Row address hold time	10				ns	
t <sub>ASC</sub>	Column address set-up time	0				ns	
t <sub>CAH</sub>	Column address hold time	10				ns	
t <sub>RAL</sub>	Column address to RAS\ lead time	30				ns	
t <sub>RCS</sub>	Read command set-up time	0				ns	
t <sub>RCH</sub>	Read command hold time referenced to CAS\	0				ns	8
t <sub>RRH</sub>	Read command hold time referenced to RAS\	0				ns	8
t <sub>WCH</sub>	Write command hold time	10				ns	
t <sub>WP</sub>	Write command pulse width	10				ns	
t <sub>RWL</sub>	Write command to RAS\ lead time	15				ns	
t <sub>CWL</sub>	Write command to CAS\ lead time	15				ns	



**ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS<sup>1,2</sup>**  
(CONTINUED)

SYMBOL	PARAMETER	-60		-70		UNITS	NOTES
		MIN	MAX	MIN	MAX		
t <sub>DS</sub>	Data set-up time	0				ns	9
t <sub>DH</sub>	Data hold time	10				ns	9
t <sub>REF</sub>	Refresh period		128			ms	
t <sub>WCS</sub>	Write command set-up time	0				ns	7
t <sub>CWD</sub>	CAS\ to W\ delay time	40				ns	7
t <sub>RWD</sub>	RAS\ to W\ delay time	85				ns	7
t <sub>AWD</sub>	Column address to W\ delay time	55				ns	7
t <sub>CPWD</sub>	CAS\ precharge to W\ delay time	60				ns	
t <sub>CSR</sub>	CAS\ set-up time (CAS\-before-RAS\ refresh)	5				ns	
t <sub>CHR</sub>	CAS\ hold time (CAS\-before-RAS\ refresh)	10				ns	
t <sub>RPC</sub>	RAS\ to CAS\ precharge time	5				ns	
t <sub>CPA</sub>	Access time from CAS\ precharge		35			ns	3
t <sub>PC</sub>	Fast Page cycle time	40				ns	
t <sub>PRWC</sub>	Fast Page read-modify-write cycle time	85				ns	
t <sub>CP</sub>	CAS\ precharge time (Fast Page Cycle)	10				ns	
t <sub>RASP</sub>	RAS\ pulse width (Fast Page Cycle)	60	200K			ns	
t <sub>RHCP</sub>	RAS\ hold time from CAS\ precharge	35				ns	
t <sub>OEA</sub>	OE\ access time		15			ns	
t <sub>OED</sub>	OE\ to data delay	15				ns	
t <sub>OEZ</sub>	Output buffer turn off delay time from OE\	0	15			ns	6
t <sub>OEH</sub>	OE\ command hold time	15				ns	
t <sub>WTS</sub>	Write command set-up time (Test mode in)	10				ns	11
t <sub>WTH</sub>	Write command hold time (Test mode in)	10				ns	11
t <sub>WRP</sub>	W\ to RAS\ precharge time (C\-B-R\ refresh)	10				ns	
t <sub>WRH</sub>	W\ to RAS\ hold time (C\-B-R\ refresh)	10				ns	
t <sub>RASS</sub>	RAS\ pulse width (C\-B-R\ self refresh)	100				us	13, 14, 15
t <sub>RPS</sub>	RAS\ precharge time (C\-B-R\ self refresh)	110				ns	13, 14, 15
t <sub>CHS</sub>	CAS\ hold time (C\-B-R\ self refresh)	-50				ns	13, 14, 15



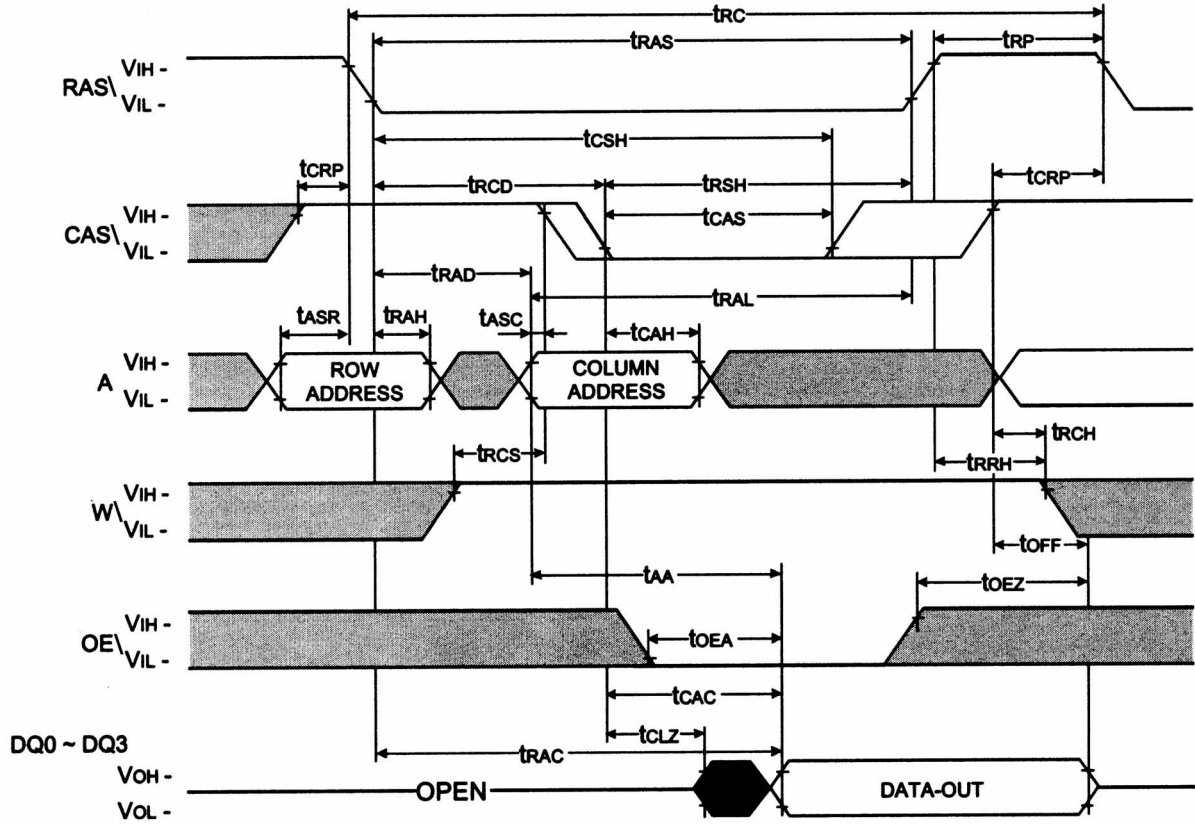
## TEST MODE CYCLE<sup>11</sup>

SYMBOL	PARAMETER	-60		-70		UNITS	NOTES
		MIN	MAX	MIN	MAX		
t <sub>RC</sub>	Random read or write cycle time	115				ns	
t <sub>RWC</sub>	Read-modify-write cycle time	160				ns	
t <sub>RAC</sub>	Access time from RAS\		65			ns	3, 4, 10, 12
t <sub>CAC</sub>	Access time from CAS\		20			ns	3, 4, 5, 12
t <sub>AA</sub>	Access time from column address		35			ns	3, 10, 12
t <sub>RAS</sub>	RAS\ pulse width	65	10K			ns	
t <sub>CAS</sub>	CAS\ pulse width	20	10K			ns	
t <sub>RSH</sub>	RAS\ hold time	20				ns	
t <sub>CSH</sub>	CAS\ hold time	65				ns	
t <sub>RAL</sub>	Column address to RAS\ lead time	35				ns	
t <sub>CWD</sub>	CAS\ to W\ delay time	45				ns	7
t <sub>RWD</sub>	RAS\ to W\ delay time	90				ns	7
t <sub>AWD</sub>	Column address to W\ delay time	60				ns	7
t <sub>CPWD</sub>	CAS\ precharge to W\ delay time	65				ns	
t <sub>PC</sub>	Fast Page cycle time	45				ns	
t <sub>PRWC</sub>	Fast Page read-modify-write time	90				ns	
t <sub>RASP</sub>	RAS\ pulse width (Fast Page Cycle)	65	200K			ns	
t <sub>CPA</sub>	Access time from CAS\ precharge		40			ns	3
t <sub>OEa</sub>	OE\ access time		20			ns	
t <sub>OED</sub>	OE\ to data delay	20				ns	
t <sub>OEh</sub>	OE\ command hold time	20				ns	

### NOTES:

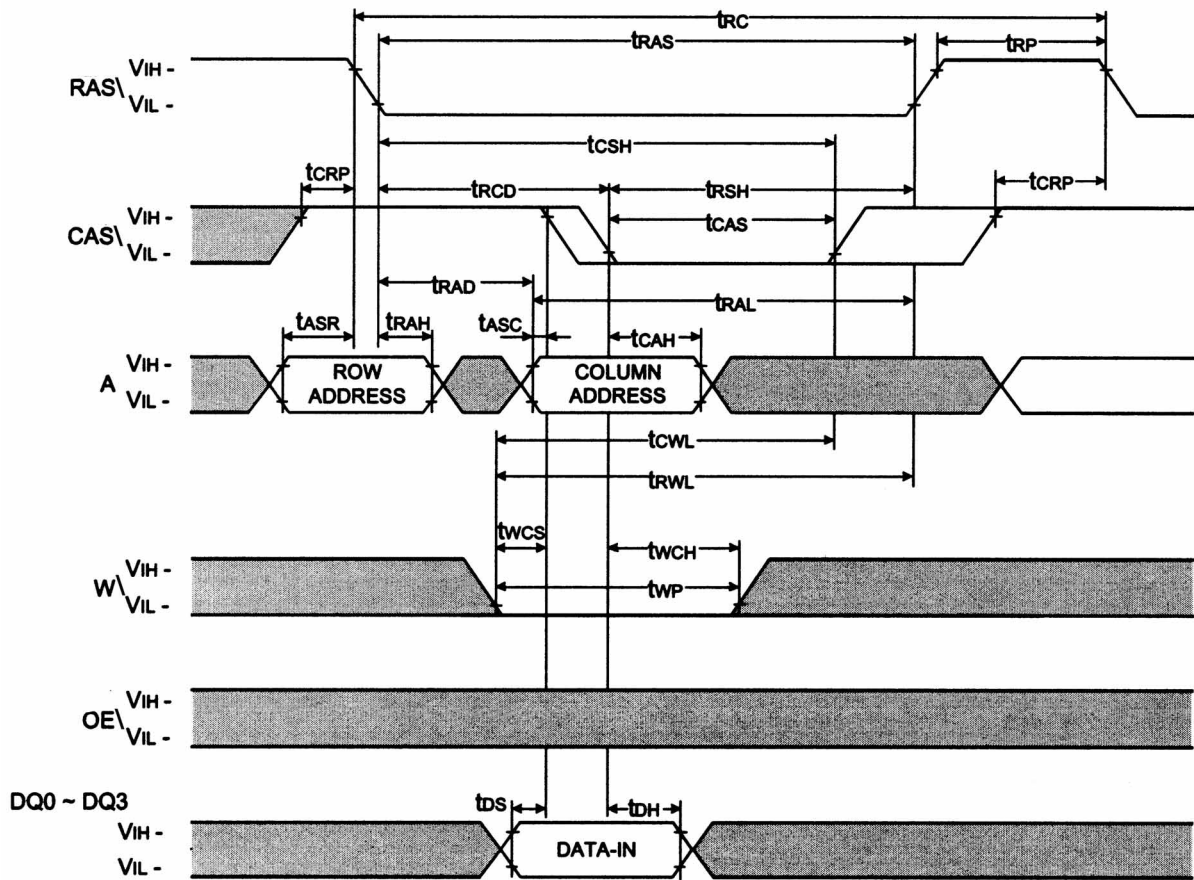
1. An initial pause of 200us is required after power-up followed by an 8 RAS\-only refresh or CAS\-before-RAS\ refresh cycles before proper device operation is achieved.
2. V<sub>IH</sub>(MIN) and V<sub>IL</sub>(MAX) are reference levels for measuring timing of input signals. Transition times are measured between V<sub>IH</sub>(MIN) and V<sub>IL</sub>(MAX) and are assumed to be 5ns for all inputs.
3. Measured with a load equivalent to 1 TTL loads and 100pF.
4. Operation within the t<sub>RCD</sub>(MAX) limit insures that t<sub>RAC</sub>(MAX) can be met. t<sub>RCD</sub>(MAX) is specified as a reference point only. If t<sub>RCD</sub> is greater than the specified t<sub>RCD</sub>(MAX) limit, then access time is controlled exclusively by t<sub>CAC</sub>.
5. Assumes that t<sub>RCD</sub> ≥ t<sub>RCD</sub>(MAX).
6. t<sub>OFF</sub>(MIN) and t<sub>OEZ</sub>(MAX) define the time at which the output achieves the open circuit condition and are not referenced V<sub>OH</sub> or V<sub>OL</sub>.
7. t<sub>WCS</sub>, t<sub>RWD</sub>, t<sub>CWD</sub> and t<sub>AWD</sub> are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If t<sub>WCS</sub> ≥ t<sub>WCS</sub>(MIN), the cycle is an early write cycle and the data output will remain high impedance for the duration of the cycle. If t<sub>CWD</sub> ≥ t<sub>CWD</sub>(MIN), t<sub>RWD</sub> ≥ t<sub>RWD</sub>(MIN) and t<sub>AWD</sub> ≥ t<sub>AWD</sub>(MIN), then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
8. Either t<sub>RCH</sub> or t<sub>RRH</sub> must be satisfied for a read cycle.
9. These parameters are referenced to CAS\ falling edge in early write cycles and to W\ falling edge in read-modify-write cycles.
10. Operation within the t<sub>RAD</sub>(MAX) limit insures that t<sub>RAC</sub>(MAX) can be met. t<sub>RAD</sub>(MAX) is specified as a reference point only. If t<sub>RAD</sub> is greater than the specified t<sub>RAS</sub>(MAX) limit, then access time is controlled by t<sub>AA</sub>.
11. These specifications are applied in the test mode.
12. In test mode read cycle, the value of t<sub>RAC</sub>, t<sub>AA</sub>, t<sub>CAC</sub> is delayed by 2ns to 5ns for the specified values. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.
13. If t<sub>RASS</sub> ≥ 100 us, then RAS\ precharge time must use t<sub>RPS</sub> instead of t<sub>RP</sub>.
14. For RAS\-only refresh and burst CAS\-before-RAS\ refresh mode, 2048 cycles of burst refresh must be executed within 32ms before and after self refresh, in order to meet refresh specification.
15. For distributed CAS\-before-RAS\ with 15.6us interval CAS\-before-RAS\ refresh should be executed with in 15.6us immediately before and after self refresh in order to meet refresh specification.

**READ CYCLE**





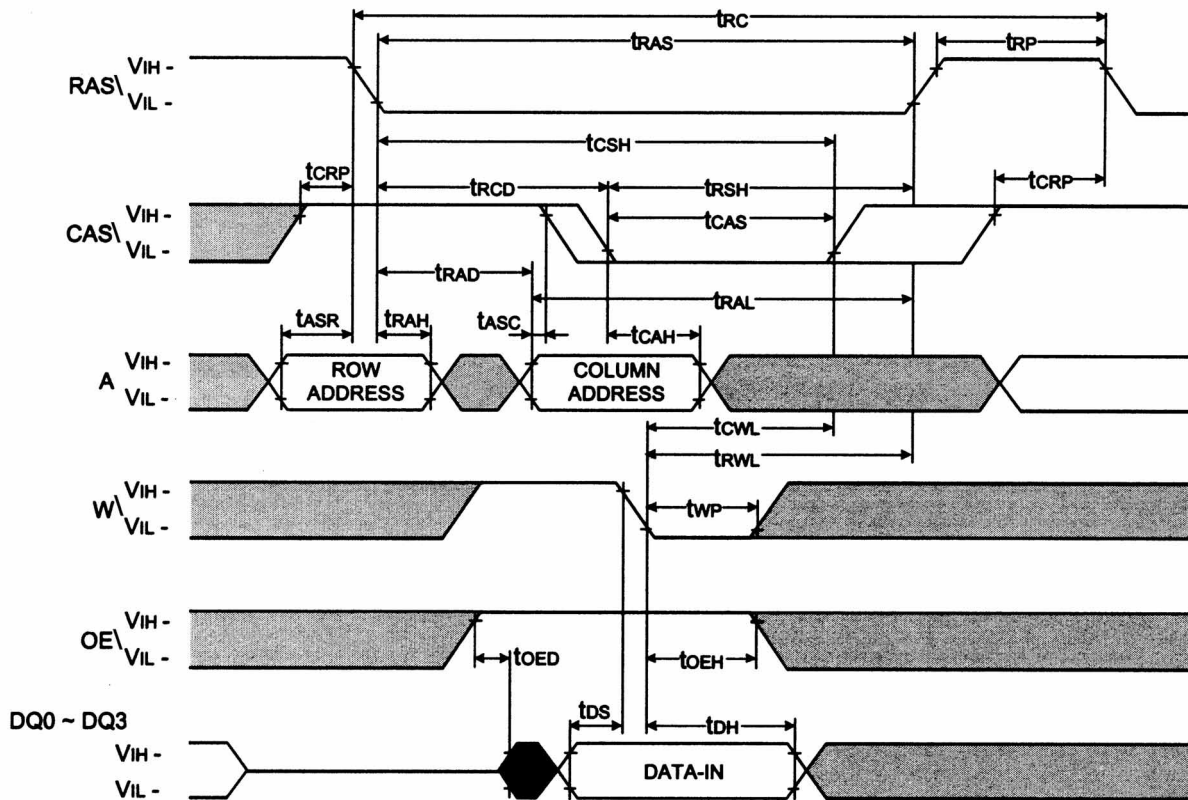
WRITE CYCLE (EARLY WRITE)  $D_{OUT} = OPEN$



 Don't care  
 Undefined

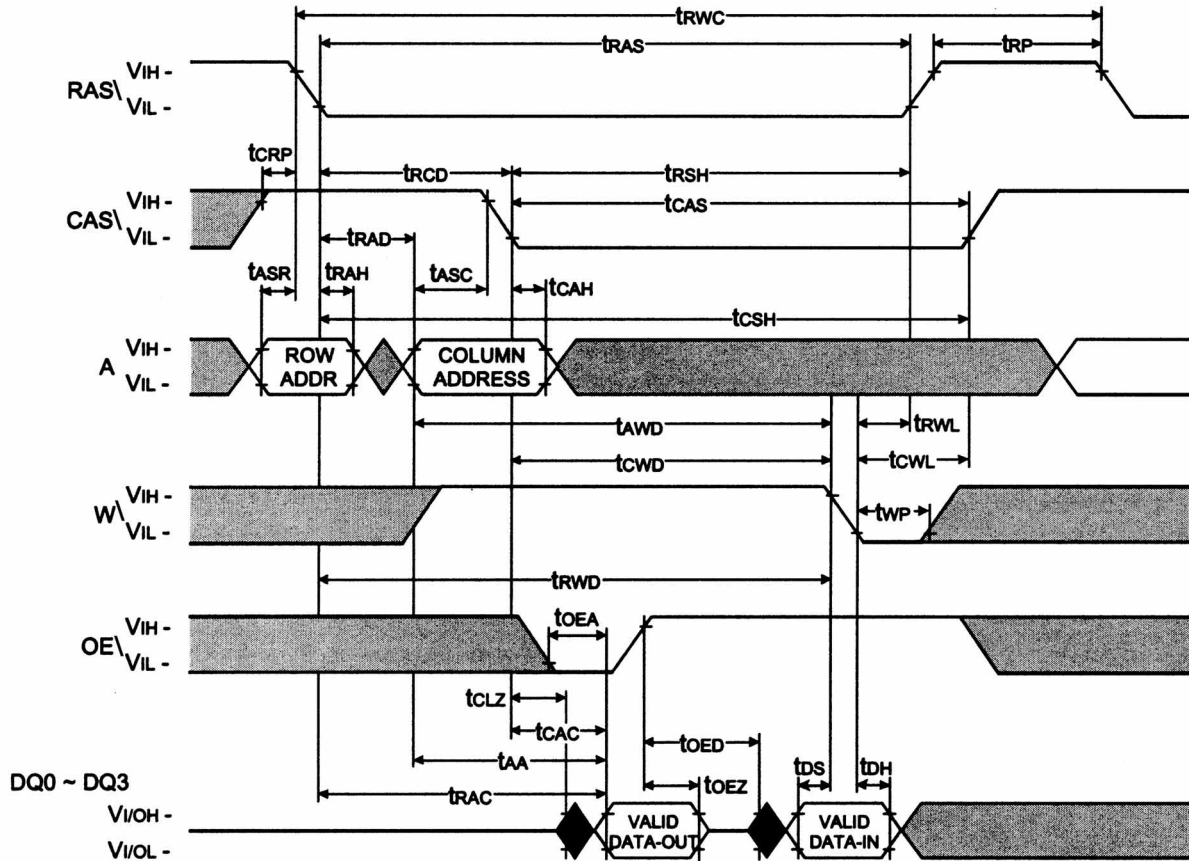


WRITE CYCLE (OE\ CONTROLLED WRITE)  $D_{OUT} = OPEN$



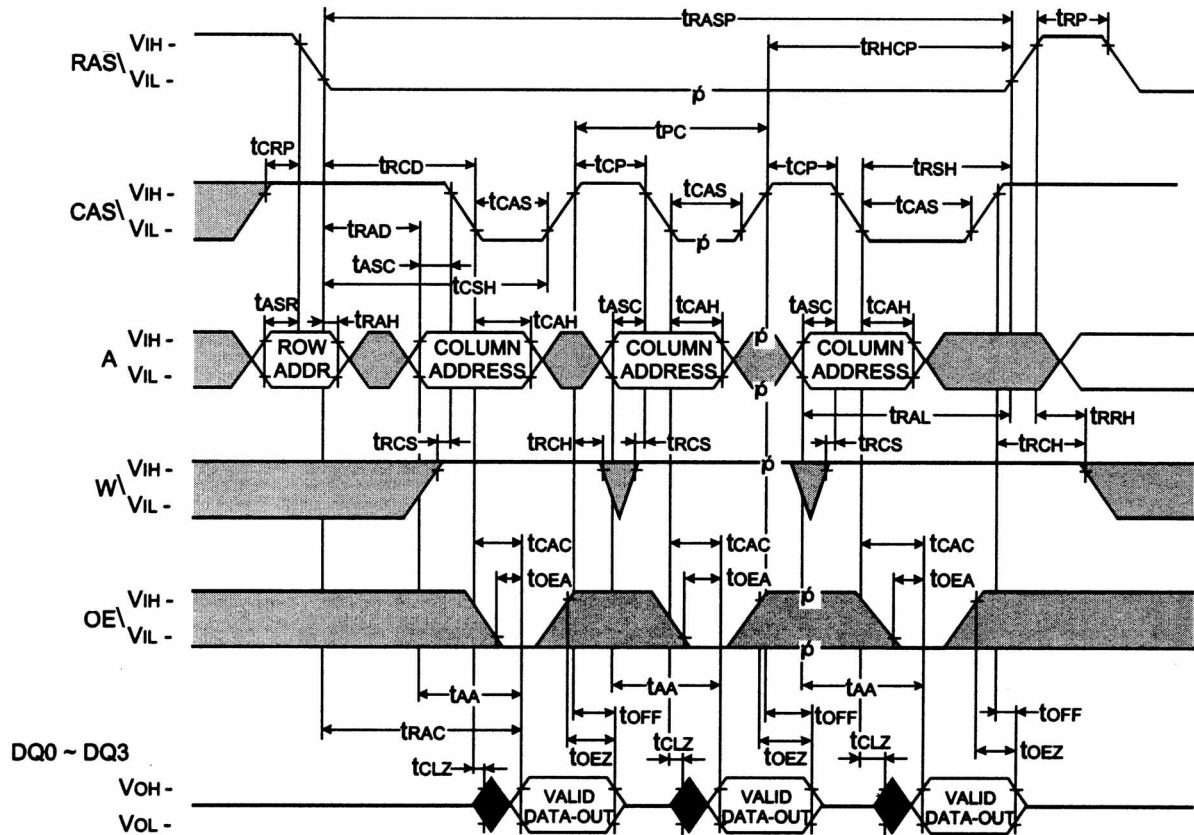
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**READ-MODIFY-WRITE CYCLE**



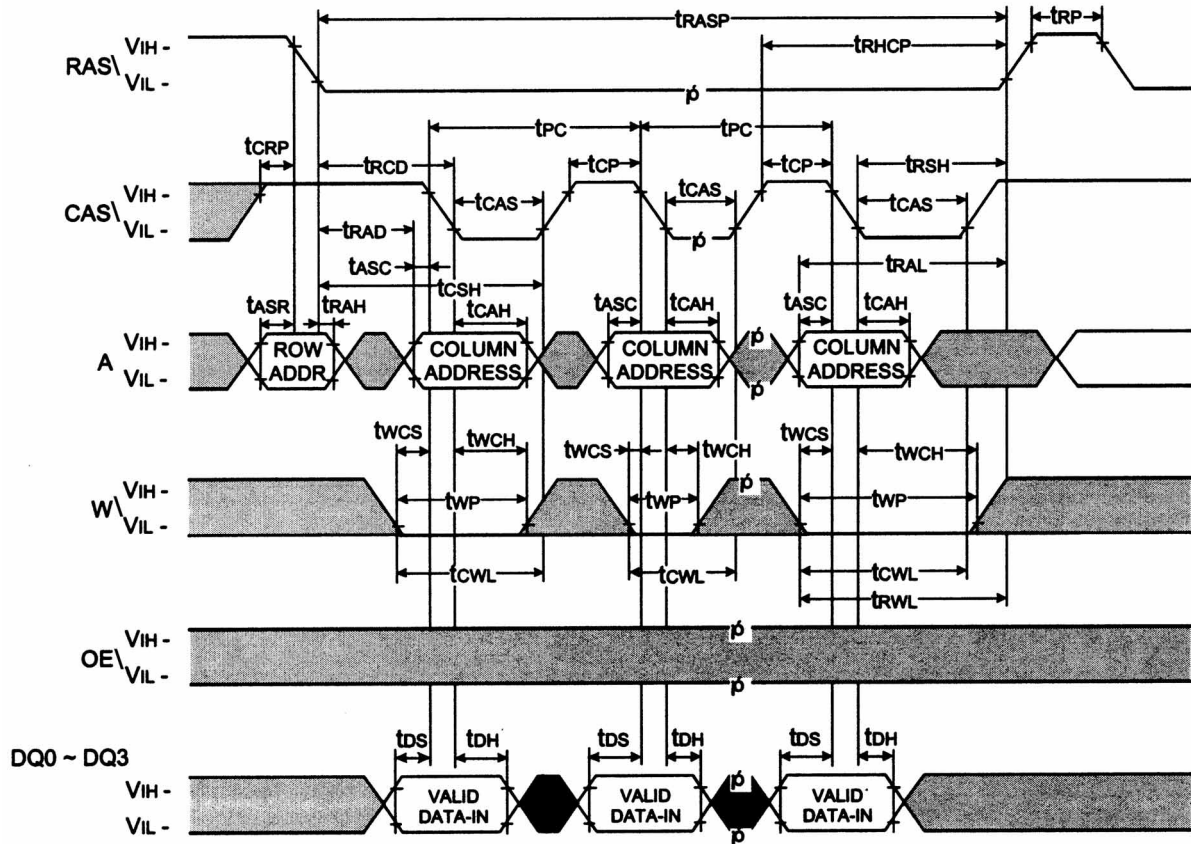
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■ Undefined



**FAST PAGE READ CYCLE**



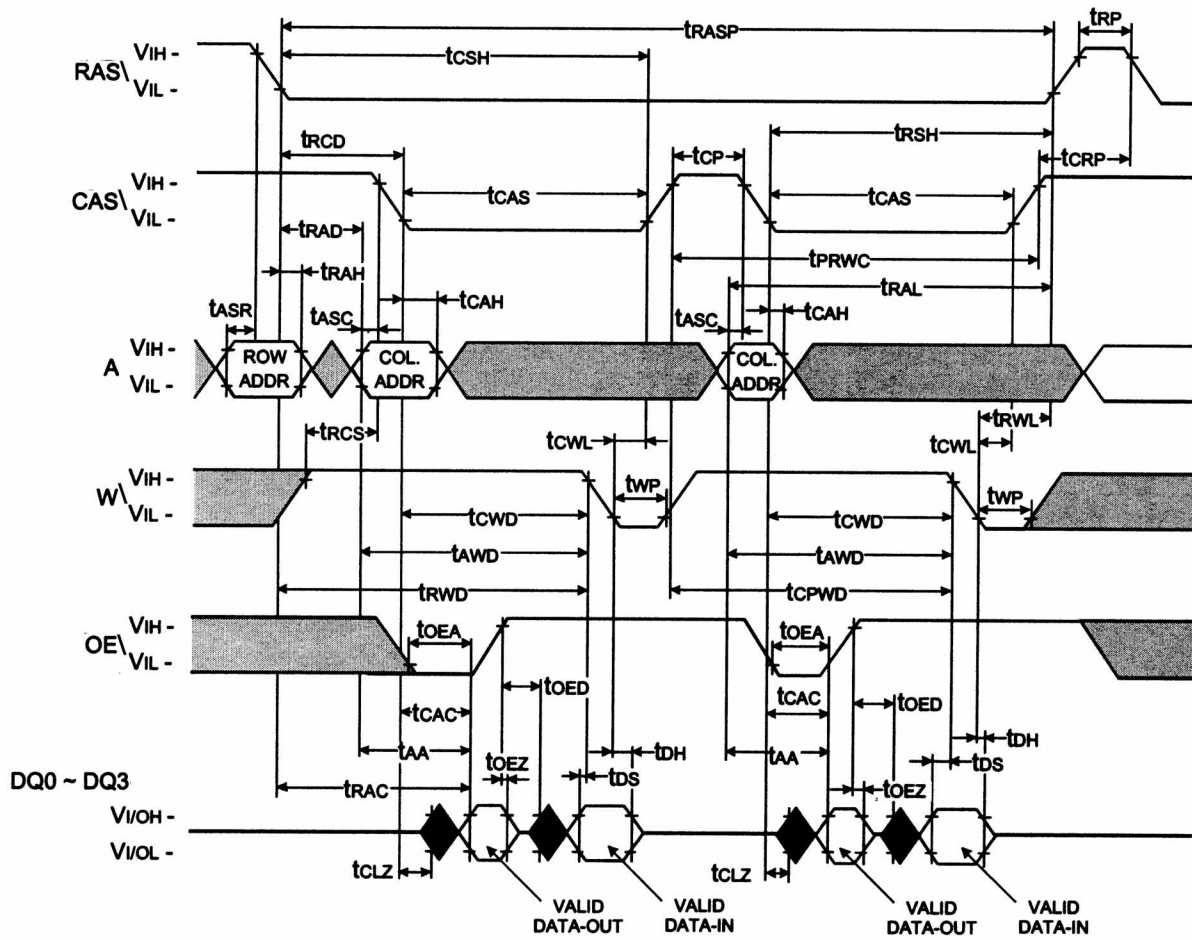
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**FAST PAGE WRITE CYCLE (EARLY WRITE)  $D_{OUT} = OPEN$**



 Don't care  
 Undefined

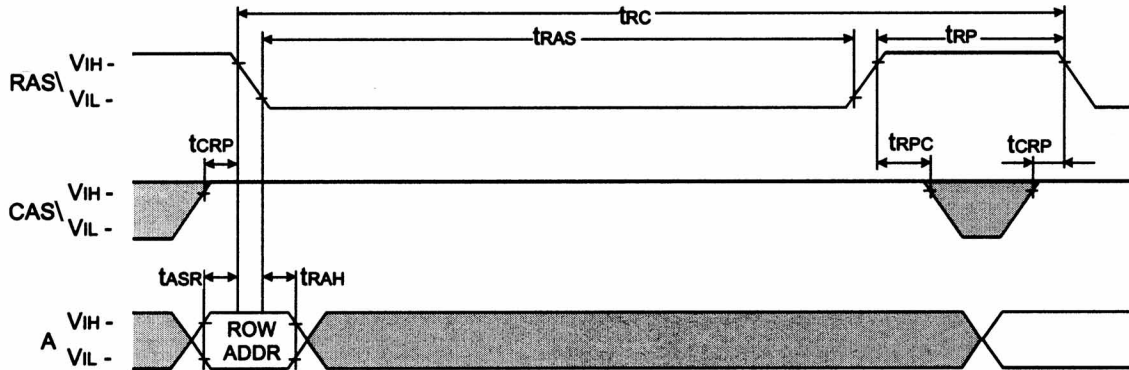
**FAST PAGE READ-MODIFY-WRITE CYCLE**



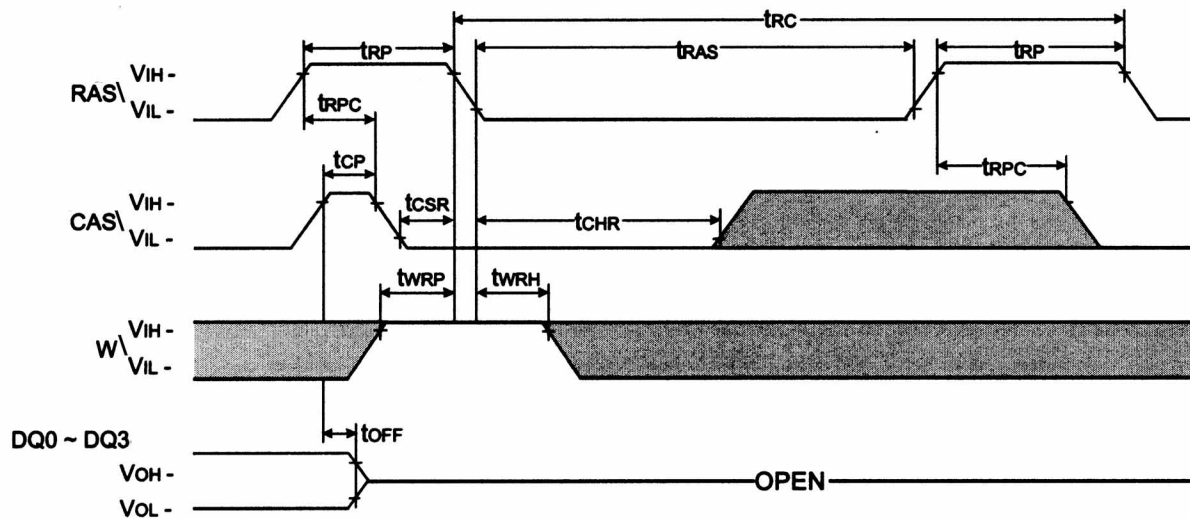
■ Don't care  
■ Undefined



**RAS\ONLY REFRESH CYCLE (W, OE\, D<sub>IN</sub> = DON'T CARE; D<sub>OUT</sub> = OPEN)**

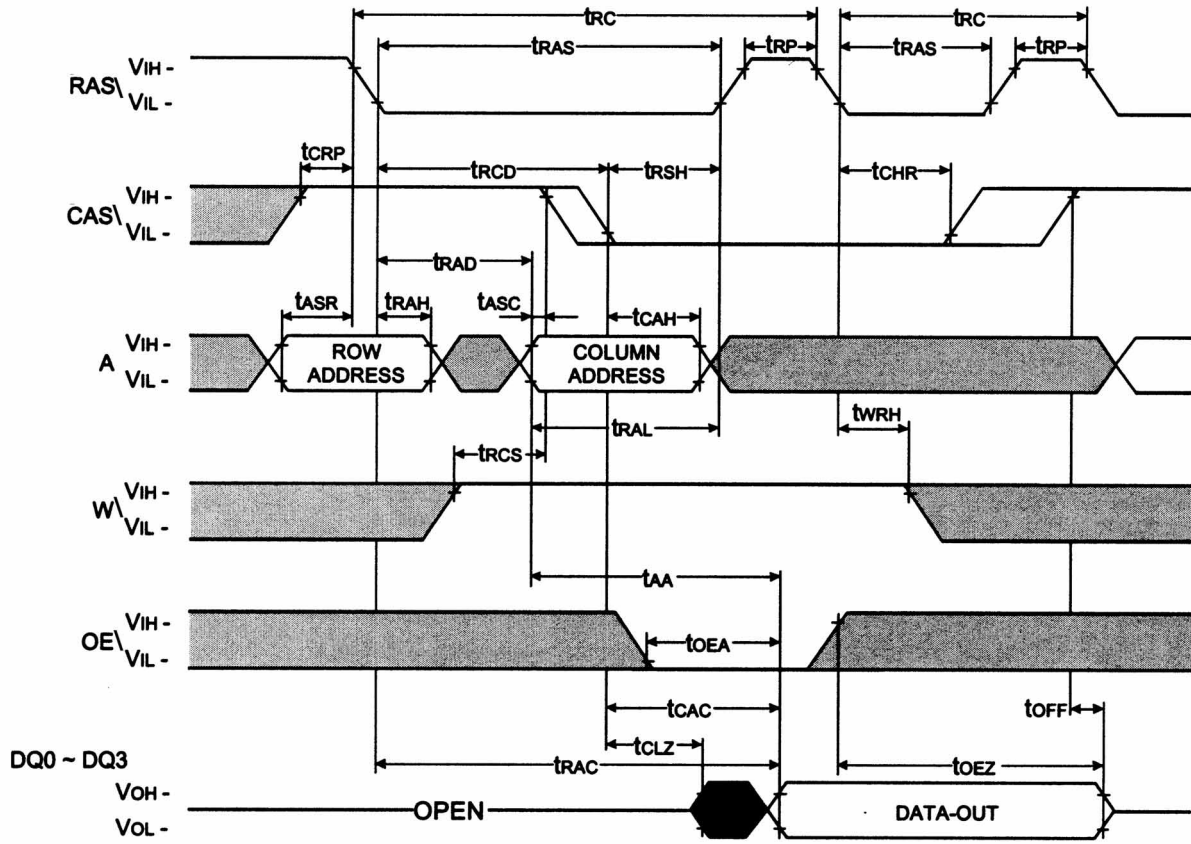


**CAS\BEFORE-RAS\ REFRESH CYCLE (OE\, A = DON'T CARE)**



 Don't care  
 Undefined

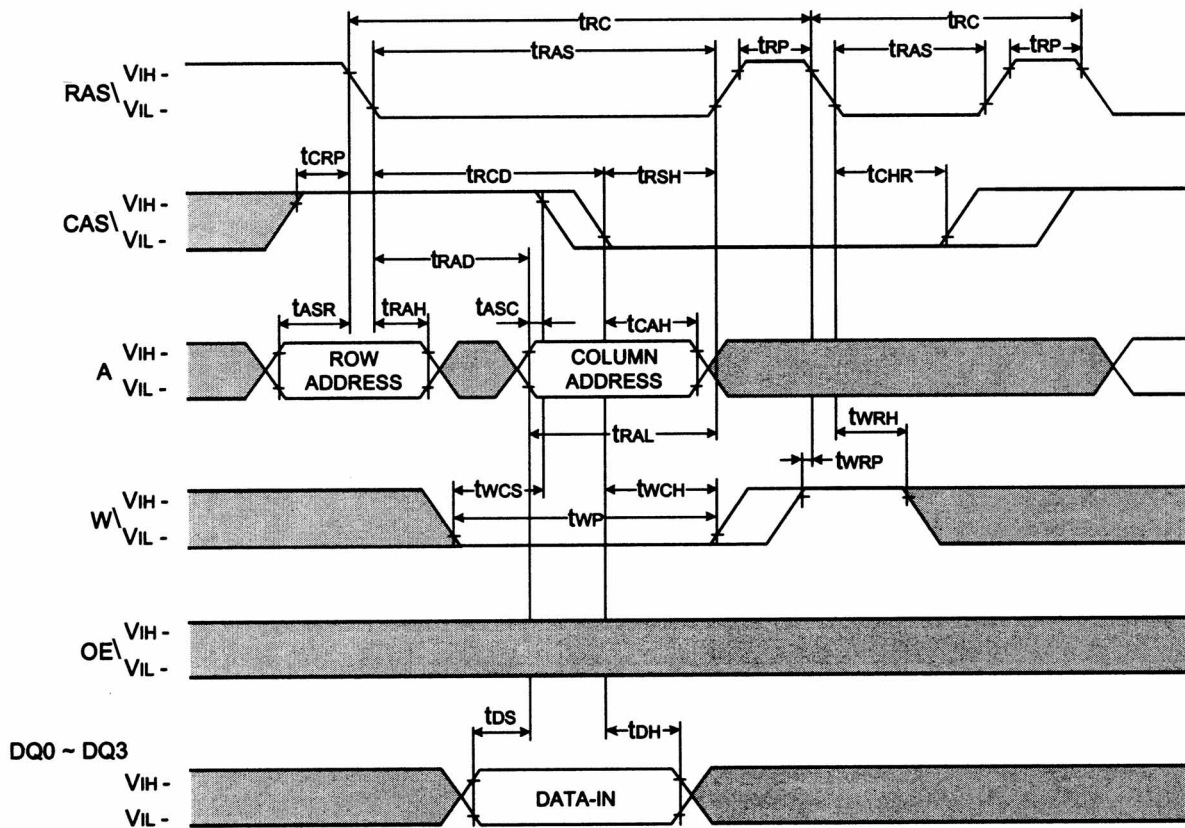
**HIDDEN REFRESH CYCLE (READ)**



■ Don't care  
■ Undefined

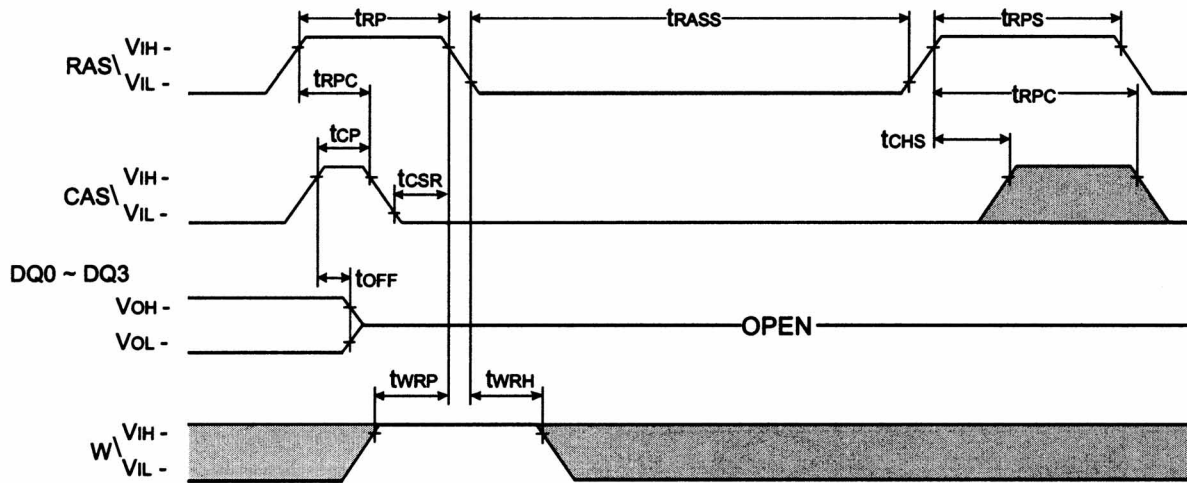


HIDDEN REFRESH CYCLE (WRITE)  $D_{OUT} = OPEN$

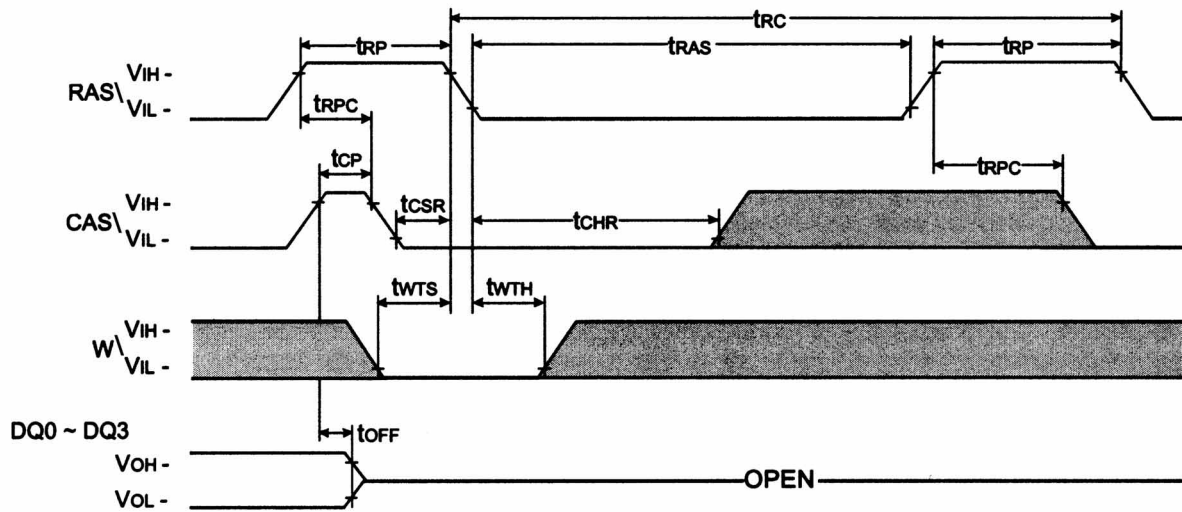


■ Don't care  
■ Undefined

**CAS\BEFORE-RAS\ SELF REFRESH CYCLE (OE\, A = DON'T CARE)**



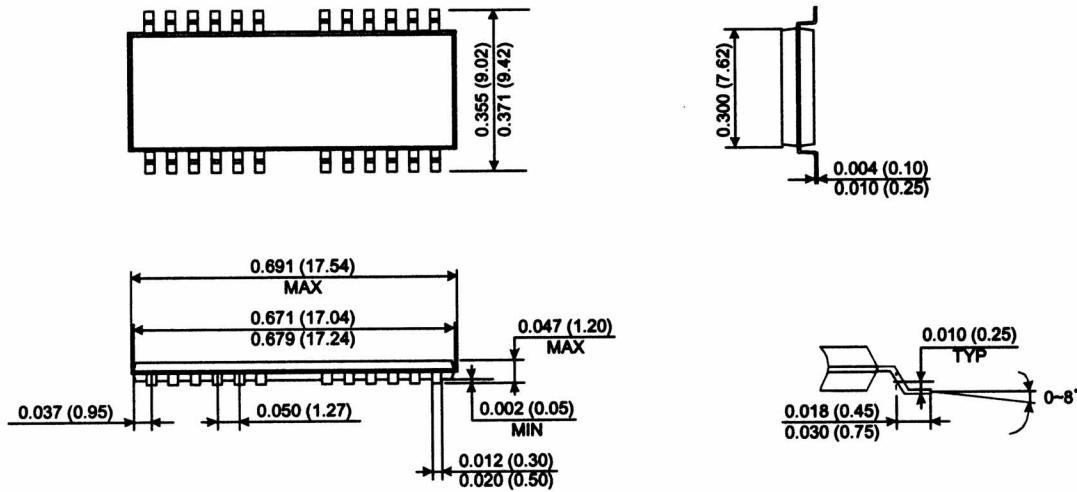
**TEST MODE IN CYCLE (OE\, A = DON'T CARE)**



■ Don't care  
■ Undefined

**MECHANICAL DEFINITIONS\***

Package Designator DG



\*All measurements are in inches (millimeters).



Austin Semiconductor, Inc.

16 Meg FPM DRAM  
AS4LC4M4

## ORDERING INFORMATION

EXAMPLE: AS4LC4M4DG-6/XT

Device Number	Package Type	Speed	Process
AS4LC4M4	DG	-6	/*
AS4LC4M4	DG	-7	/*

### \*AVAILABLE PROCESSES

IT = Industrial Temperature Range

-40°C to +85°C

XT = Extended Temperature Range

-55°C to +125°C